

N-channel 40 V, 1.1 m $\Omega$ , 280 A logic level MOSFET in SOT1023A enhanced package for UL2595, using NextPower-S3 Schottky-Plus technology

23 May 2018

Product data sheet

#### 1. General description

SOT1023A with improved creepage and clearance to meet UL2595 requirements 280 Amp, logic level gate drive N-channel enhancement mode MOSFET in 150 °C LFPAK56 package using advanced TrenchMOS Superjunction technology. This product has been designed and qualified for high performance power switching applications.

#### 2. Features and benefits

- Improved creepage and clearance meets the requirements of UL2595
- 280 A capability
- Avalanche rated, 100% tested at I<sub>AS</sub> = 190 A
- · NextPower-S3 technology delivers 'superfast switching with soft recovery'
- Low Q<sub>RR</sub>, Q<sub>G</sub> and Q<sub>GD</sub> for high system efficiency and low EMI designs
- Schottky-Plus body-diode, gives soft switching without the associated high I<sub>DSS</sub> leakage
- Optimised for 4.5 V gate drive utilising NextPower-S3 Superjunction technology
- High reliability LFPAK (Power SO8) package, copper-clip, solder die attach and qualified to 150 °C
- Exposed leads can be wave soldered, visual solder joint inspection and high quality solder joints
- Low parasitic inductance and resistance

### 3. Applications

- Brushed and brushless motor control
- Battery powered appliances where enhanced creepage and clearance is required to meet UL2595
- For non-UL2595 applications please use PSMN1R0-40YLD

### 4. Quick reference data

#### Table 1. Quick reference data

| Symbol            | Parameter                        | Conditions  |     | Min | Тур  | Max | Unit |
|-------------------|----------------------------------|---|-----|-----|------|-----|------|
| V <sub>DS</sub>   | drain-source voltage             | 25 °C ≤ T <sub>j</sub> ≤ 150 °C   |     | -   | -    | 40  | V    |
| I <sub>D</sub>    | drain current                    | V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>                              | [1] | -   | -    | 280 | А    |
| P <sub>tot</sub>  | total power dissipation          | T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>  |     | -   | -    | 164 | W    |
| Tj                | junction temperature             |   |     | -55 | -    | 150 | °C   |
| Static chara      | icteristics                      | ·   | ·   | ·   | ·    |     |      |
| R <sub>DSon</sub> | drain-source on-state resistance | V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C;<br>Fig. 10; Fig. 11 |     | -   | 1.1  | 1.4 | mΩ   |
|                   |                                  | V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C;<br>Fig. 10; Fig. 11  |     | -   | 0.93 | 1.1 | mΩ   |

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| Symbol              | Parameter         | Conditions   | Min | Тур | Мах | Unit |
|---------------------|-------------------|--|-----|-----|-----|------|
| Dynamic chara       | acteristics       |  |     |     |     |      |
| Q <sub>GD</sub>     | gate-drain charge | $I_D = 25 \text{ A}; V_{DS} = 20 \text{ V}; V_{GS} = 4.5 \text{ V};$ | -   | 17  | -   | nC   |
| Q <sub>G(tot)</sub> | total gate charge | Fig. 12; Fig. 13   | -   | 59  | -   | nC   |

[1] 280A continuous current has been successfully demonstrated during application tests. Practically, the current will be limited by PCB, thermal design and operating temperature.

### 5. Pinning information

| Table 2. | . Pinning inf | ormation                          |                              |                |
|----------|---------------|-----------------------------------|------------------------------|----------------|
| Pin      | Symbol        | Description                       | Simplified outline           | Graphic symbol |
| 1        | S             | source                            |                              | D              |
| 2        | S             | source                            |                              |                |
| 3        | S             | source                            |                              | G-UFA          |
| 4        | G             | gate                              |                              | mbb076 S       |
| mb       | D             | mounting base; connected to drain | LFPAK56-UL2595<br>(SOT1023A) |                |

### 6. Ordering information

| Table 3. Ordering information |                    |   |          |  |  |  |
|-------------------------------|--------------------|---|----------|--|--|--|
| Type number                   | Package            |   |          |  |  |  |
|                               | Name               | Description   | Version  |  |  |  |
| PSMN1R0-40ULD                 | LFPAK56-UL<br>2595 | plastic, single-ended surface-mounted package (LFPAK56); 4 leads; 1.27 mm pitch | SOT1023A |  |  |  |

### 7. Marking

| Table 4. Marking codes |              |  |  |  |  |
|------------------------|--------------|--|--|--|--|
| Type number            | Marking code |  |  |  |  |
| PSMN1R0-40ULD          | ID04UL       |  |  |  |  |

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### 8. Limiting values

#### Table 5. Limiting values

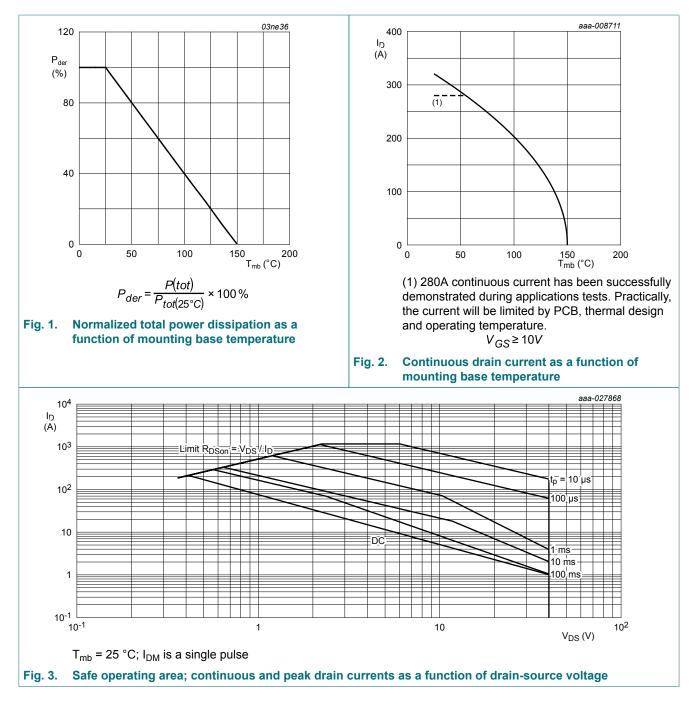
In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol               | Parameter   | Conditions   |     | Min | Max  | Unit |
|----------------------|---|--|-----|-----|------|------|
| V <sub>DS</sub>      | drain-source voltage                                | 25 °C ≤ T <sub>j</sub> ≤ 150 °C  |     | -   | 40   | V    |
| V <sub>DSM</sub>     | peak drain-source<br>voltage                        | $t_p \le 20 \text{ ns; } f \le 500 \text{ kHz; } E_{DS(AL)} \le 200 \text{ nJ;}$ pulsed  |     | -   | 45   | V    |
| V <sub>DGR</sub>     | drain-gate voltage                                  | 25 °C ≤ T <sub>j</sub> ≤ 150 °C; R <sub>GS</sub> = 20 kΩ   |     | -   | 40   | V    |
| V <sub>GS</sub>      | gate-source voltage                                 |  |     | -20 | 20   | V    |
| P <sub>tot</sub>     | total power dissipation                             | T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>   |     | -   | 164  | W    |
| I <sub>D</sub>       | drain current                                       | V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>   | [1] | -   | 280  | А    |
|                      |   | V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 100 °C; <u>Fig. 2</u>  |     | -   | 198  | А    |
| I <sub>DM</sub>      | peak drain current                                  | pulsed; $t_p \le 10 \ \mu s$ ; $T_{mb} = 25 \ ^{\circ}C$ ; Fig. 3  |     | -   | 1168 | А    |
| T <sub>stg</sub>     | storage temperature                                 |  |     | -55 | 150  | °C   |
| Tj                   | junction temperature                                |  |     | -55 | 150  | °C   |
| T <sub>sld(M)</sub>  | peak soldering<br>temperature                       |  |     | -   | 260  | °C   |
| V <sub>ESD</sub>     | electrostatic discharge voltage                     | НВМ  |     | 2   | -    | kV   |
| Source-drain         | n diode   | 1  | 1   |     |      |      |
| I <sub>S</sub>       | source current                                      | T <sub>mb</sub> = 25 °C  |     | -   | 165  | А    |
| I <sub>SM</sub>      | peak source current                                 | pulsed; $t_p \le 10 \ \mu s$ ; $T_{mb} = 25 \ ^{\circ}C$   |     | -   | 1284 | А    |
| Avalanche r          | uggedness   |  |     |     |      |      |
| E <sub>DS(AL)S</sub> | non-repetitive drain-<br>source avalanche<br>energy | $I_D$ = 85 A; V <sub>sup</sub> ≤ 40 V; R <sub>GS</sub> = 50 Ω;<br>V <sub>GS</sub> = 10 V; T <sub>j(init)</sub> = 25 °C; unclamped;<br>t <sub>p</sub> = 0.26 ms | [2] | -   | 570  | mJ   |
|                      |   | $I_D$ = 25 A; V <sub>sup</sub> ≤ 40 V; R <sub>GS</sub> = 50 Ω;<br>V <sub>GS</sub> = 10 V; T <sub>j(init)</sub> = 25 °C; unclamped;<br>t <sub>p</sub> = 3.8 ms  | [2] | -   | 2328 | mJ   |
| I <sub>AS</sub>      | non-repetitive avalanche current                    | $V_{sup} \le 40 \text{ V}; V_{GS} = 10 \text{ V}; T_{j(init)} = 25 \text{ °C}; R_{GS} = 50 \Omega$   | [2] | -   | 190  | A    |

[1] 280A continuous current has been successfully demonstrated during application tests. Practically, the current will be limited by PCB, thermal design and operating temperature.

[2] Protected by 100% test.

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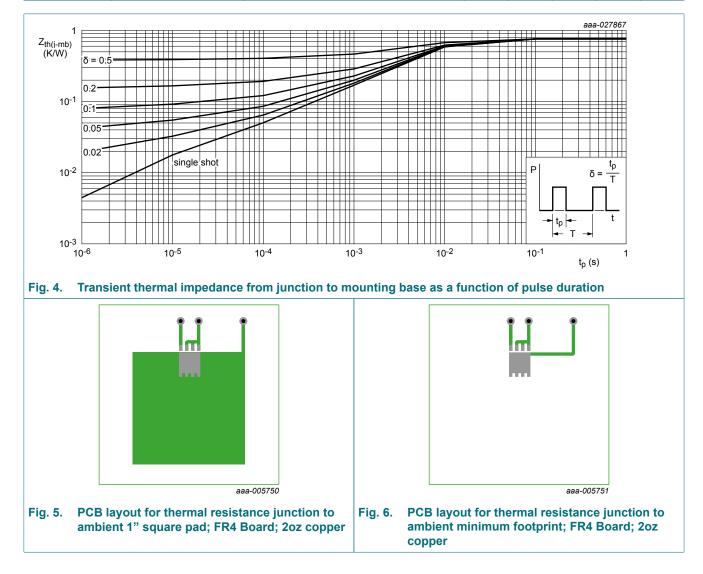


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#### 9. Thermal characteristics

| Table 6. | Thermal | characteristics |
|----------|---------|-----------------|
|----------|---------|-----------------|

| Symbol                | Parameter   | Conditions                     | Min | Тур       | Max  | Unit       |
|-----------------------|---|--------------------------------|-----|-----------|------|------------|
| R <sub>th(j-mb)</sub> | thermal resistance<br>from junction to<br>mounting base | <u>Fig. 4</u>                  | -   | 0.66      | 0.76 | K/W        |
| R <sub>th(j-a)</sub>  | thermal resistance<br>from junction to<br>ambient       | <u>Fig. 5</u><br><u>Fig. 6</u> | -   | 50<br>125 | -    | K/W<br>K/W |



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### **10. Characteristics**

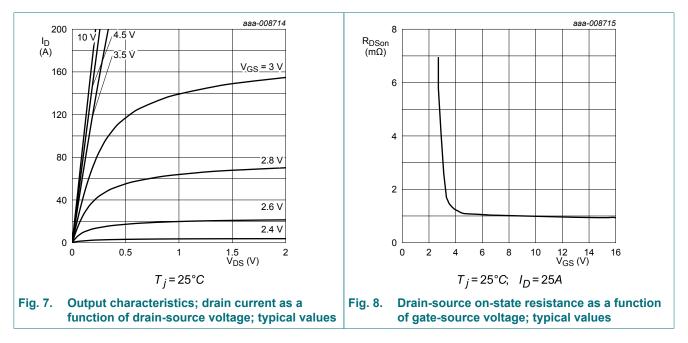
| Symbol                   | Parameter  | Conditions   | Min  | Тур  | Мах  | Unit |
|--------------------------|--|--|------|------|------|------|
| Static charac            | cteristics   |  |      |      |      |      |
| V <sub>(BR)DSS</sub>     | drain-source   | I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C                             | 40   | -    | -    | V    |
|                          | breakdown voltage  | $I_D$ = 250 µA; $V_{GS}$ = 0 V; $T_j$ = -55 °C   | 36   | -    | -    | V    |
| V <sub>GS(th)</sub>      | gate-source threshold voltage                                  | $I_{D}$ = 1 mA; $V_{DS}$ = $V_{GS}$ ; $T_{j}$ = 25 °C  | 1.05 | 1.7  | 2.2  | V    |
| ΔV <sub>GS(th)</sub> /ΔT | gate-source threshold<br>voltage variation with<br>temperature | 25 °C ≤ T <sub>j</sub> ≤ 150 °C  | -    | -5.1 | -    | mV/K |
| I <sub>DSS</sub>         | drain leakage current  | $V_{DS}$ = 32 V; $V_{GS}$ = 0 V; $T_j$ = 25 °C   | -    | -    | 1    | μA   |
|                          |  | V <sub>DS</sub> = 32 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 125 °C                             | -    | 9    | -    | μA   |
| I <sub>GSS</sub>         | gate leakage current   | V <sub>GS</sub> = 16 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C                              | -    | -    | 100  | nA   |
|                          |  | $V_{GS}$ = -16 V; $V_{DS}$ = 0 V; $T_j$ = 25 °C  | -    | -    | 100  | nA   |
| R <sub>DSon</sub>        | drain-source on-state<br>resistance                            | V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C;<br><u>Fig. 10; Fig. 11</u>  | -    | 0.93 | 1.1  | mΩ   |
|                          |  | V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 150 °C;<br><u>Fig. 10; Fig. 11</u> | -    | -    | 1.93 | mΩ   |
|                          |  | V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C;<br>Fig. 10; Fig. 11        | -    | 1.1  | 1.4  | mΩ   |
|                          |  | V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 150 °C;<br>Fig. 10; Fig. 11       | -    | -    | 2.45 | mΩ   |
| R <sub>G</sub>           | gate resistance  | f = 1 MHz  | -    | 1.3  | -    | Ω    |
| Dynamic cha              | aracteristics  | · · · · ·  | ,    |      |      | ·    |
| Q <sub>G(tot)</sub>      | total gate charge  | I <sub>D</sub> = 25 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 10 V;<br>Fig. 12; Fig. 13         | -    | 127  | -    | nC   |
|                          |  | $I_D$ = 25 A; $V_{DS}$ = 20 V; $V_{GS}$ = 4.5 V;<br>Fig. 12; Fig. 13                               | -    | 59   | -    | nC   |
|                          |  | I <sub>D</sub> = 0 A; V <sub>DS</sub> = 0 V; V <sub>GS</sub> = 10 V                                | -    | 115  | -    | nC   |
| Q <sub>GS</sub>          | gate-source charge   | $I_D = 25 \text{ A}; V_{DS} = 20 \text{ V}; V_{GS} = 4.5 \text{ V};$                               | -    | 19   | -    | nC   |
| Q <sub>GS(th)</sub>      | pre-threshold gate-<br>source charge                           | Fig. 12; Fig. 13   | -    | 12   | -    | nC   |
| Q <sub>GS(th-pl)</sub>   | post-threshold gate-<br>source charge                          |  | -    | 8    | -    | nC   |
| Q <sub>GD</sub>          | gate-drain charge  |  | -    | 17   | -    | nC   |
| V <sub>GS(pl)</sub>      | gate-source plateau voltage                                    | I <sub>D</sub> = 25 A; V <sub>DS</sub> = 20 V; <u>Fig. 12; Fig. 13</u>                             | -    | 2.7  | -    | V    |
| C <sub>iss</sub>         | input capacitance  | V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 0 V; f = 1 MHz;  | -    | 8845 | -    | pF   |
| C <sub>oss</sub>         | output capacitance   | T <sub>j</sub> = 25 °C; <u>Fig. 14</u>   | -    | 1878 | -    | pF   |
| C <sub>rss</sub>         | reverse transfer capacitance                                   |  | -    | 382  | -    | pF   |

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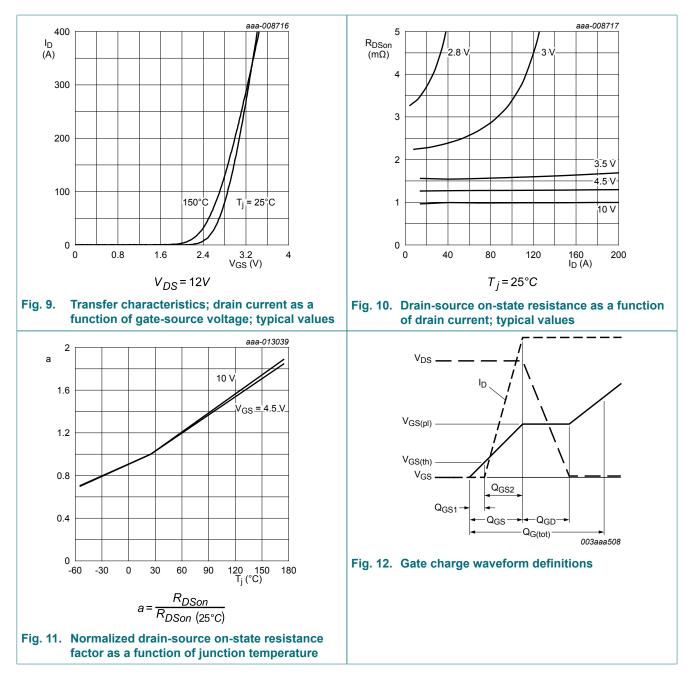
#### N-channel 40 V, 1.1 mΩ, 280 A logic level MOSFET in SOT1023A enhanced package for UL2595, using NextPower-S3 Schottky-Plus technology

| Symbol              | Parameter                  | Conditions  |     | Min | Тур  | Мах | Unit |
|---------------------|----------------------------|---|-----|-----|------|-----|------|
| t <sub>d(on)</sub>  | turn-on delay time         | $V_{DS}$ = 20 V; R <sub>L</sub> = 0.8 Ω; V <sub>GS</sub> = 4.5 V;                   |     | -   | 52   | -   | ns   |
| t <sub>r</sub>      | rise time                  | $R_{G(ext)} = 5 \Omega$   |     | -   | 62   | -   | ns   |
| t <sub>d(off)</sub> | turn-off delay time        |   |     | -   | 65   | -   | ns   |
| t <sub>f</sub>      | fall time                  |   |     | -   | 38   | -   | ns   |
| Q <sub>oss</sub>    | output charge              | V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 20 V; f = 1 MHz;<br>T <sub>j</sub> = 25 °C |     | -   | 51   | -   | nC   |
| Source-dra          | in diode                   | •   |     |     |      |     |      |
| V <sub>SD</sub>     | source-drain voltage       | $I_{S}$ = 25 A; $V_{GS}$ = 0 V; $T_{j}$ = 25 °C; <u>Fig. 15</u>                     |     | -   | 0.78 | 1.2 | V    |
| t <sub>rr</sub>     | reverse recovery time      | $I_{S}$ = 25 A; dI <sub>S</sub> /dt = -100 A/µs; V <sub>GS</sub> = 0 V;             |     | -   | 48   | -   | ns   |
| Q <sub>r</sub>      | recovered charge           | V <sub>DS</sub> = 20 V; <u>Fig. 16</u>  | [1] | -   | 67   | -   | nC   |
| t <sub>a</sub>      | reverse recovery rise time |   |     | -   | 28.6 | -   | ns   |
| t <sub>b</sub>      | reverse recovery fall time |   |     | -   | 23.8 | -   | ns   |

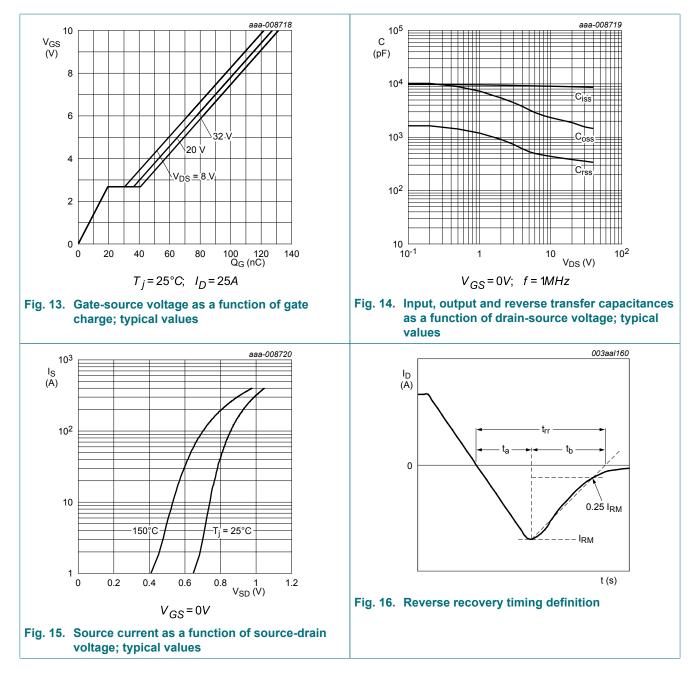
[1] includes capacitive recovery



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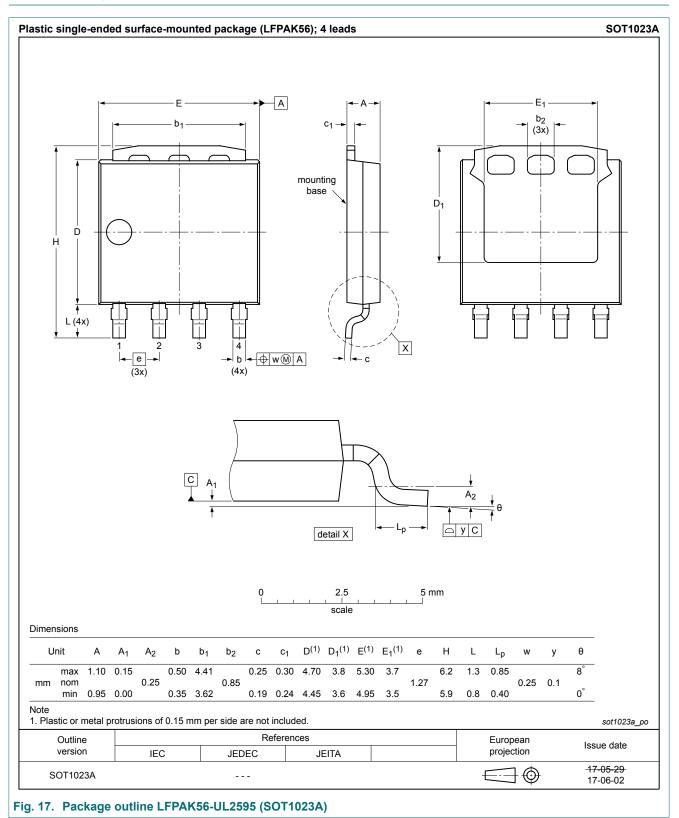


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N-channel 40 V, 1.1 mΩ, 280 A logic level MOSFET in SOT1023A enhanced package for UL2595, using NextPower-S3 Schottky-Plus technology

### 11. Package outline



#### N-channel 40 V, 1.1 mΩ, 280 A logic level MOSFET in SOT1023A enhanced package for UL2595, using NextPower-S3 Schottky-Plus technology

### 12. Legal information

#### Data sheet status

| Document status [1][2]            | Product<br>status [3] | Definition  |
|-----------------------------------|-----------------------|---|
| Objective [short]<br>data sheet   | Development           | This document contains data from<br>the objective specification for<br>product development. |
| Preliminary [short]<br>data sheet | Qualification         | This document contains data from the preliminary specification.                             |
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[1] Please consult the most recently issued document before initiating or completing a design.

- [2] The term 'short data sheet' is explained in section "Definitions".
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PSMN1R0-40ULD

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### PSMN1R0-40ULD

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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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